

Silicon Carbide (SiC) MOSFET, M1, TO-247-4L 1700 V, 28 mOhm NTH4L028N170M1

Features

- Typ. $R_{DS(on)} = 28 \text{ m}\Omega @ V_{GS} = 20 \text{ V}$
- Ultra Low Gate Charge (Q_{G(tot)} = 200 nC)
- High Speed Switching with Low Capacitance (C_{oss} = 200 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Typical Applications

- UPS
- DC/DC Converter
- Boost Converter

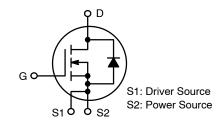
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage		V_{DSS}	V _{DSS} 1700		
Gate-to-Source Voltage			V_{GS}	-15/+25	V
	Recommended Operation Values of Gate-to-Source Voltage $T_C < 175^{\circ}C$		V_{GSop}	-5/+20	V
Continuous Drain Current (Note 1)	Steady State			81	Α
Power Dissipation (Note 1)			P _D	535	W
Continuous Drain Current (Note 1)	Steady State	T _C = 100°C	I _D	57	Α
Power Dissipation (Note 1)			P _D	267	W
Pulsed Drain Current (Note 2)	T _C = 25°C		I _{DM}	363	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	124	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 30 A, L = 1 mH) (Note 3)			E _{AS}	450	mJ
Maximum Lead Temperature for Soldering (1/8" from case for 5 s)		TL	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Repetitive rating, limited by max junction temperature.
- 3. EAS of 450 mJ is based on starting $T_J = 25^{\circ}\dot{C}$; L = 1 mH, $I_{AS} = 30$ A, $V_{DD} = 120$ V, $V_{GS} = 18$ V.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
1700 V	40 mΩ @ 20 V	81 A	



N-CHANNEL MOSFET



MARKING DIAGRAM



H4L028N170M1 = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

ORDERING INFORMATION

Device	Package	Shipping
NTH4L028N170M1	TO247-4L	30 Units / Tube

THERMAL CHARACTERISTICS

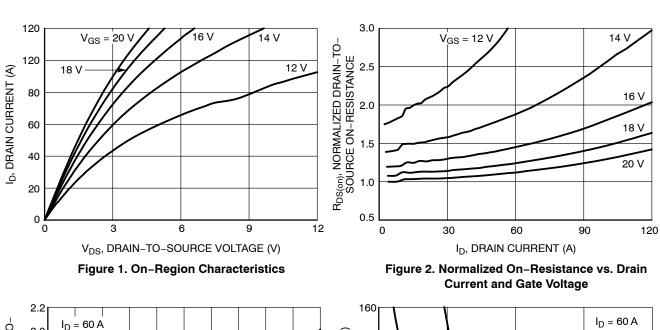
Parameter	Symbol	Max	Unit
Junction-to-Case - Steady State (Note 1)	$R_{\theta JC}$	0.28	°C/W

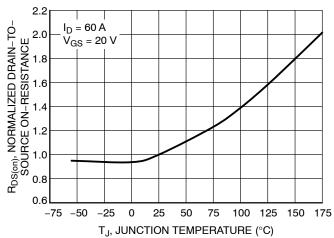
ELECTRICAL CHARACTERISTICS (T_{.1} = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA		1700	-	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J	I _D = 1 mA, referenced to 25°C		-	0.46	-	V/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25°C	-	-	100	μΑ
		V _{DS} = 1700 V	T _J = 175°C	-	-	1	mA
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = +25/–15 V,	V _{DS} = 0 V	1	-	±1	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$: 20 mA	1.8	2.75	4.3	V
Recommended Gate Voltage	V_{GOP}			-5	-	+20	V
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 20 V, I _D = 60 A	A, T _J = 25°C	-	28	40	mΩ
		V _{GS} = 20 V, I _D = 60 A	A, T _J = 175°C	-	57	-	
Forward Transconductance	9FS	V_{DS} = 20 V, I_{D}	= 60 A	-	31	-	S
CHARGES, CAPACITANCES & GATE RES	ISTANCE						
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 800 V		-	4230	-	pF
Output Capacitance	C _{OSS}			1	200	-	
Reverse Transfer Capacitance	C _{RSS}			1	10	-	
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = -5/20 \text{ V}, V_{DS} = 800 \text{ V},$ $I_{D} = 60 \text{ A}$ $f = 1 \text{ MHz}$		1	200	-	nC
Gate-to-Source Charge	Q_{GS}			1	77	-	
Gate-to-Drain Charge	Q_{GD}			1	46	-	
Gate-Resistance	R_{G}			1	5.8	-	Ω
SWITCHING CHARACTERISTICS							
Turn-On Delay Time	t _{d(ON)}	$\begin{array}{l} V_{GS}=-5/20 \text{ V,} \\ V_{DS}=1200 \text{ V,} \\ I_{D}=60 \text{ A,} \\ R_{G}=2 \Omega \\ \text{inductive load} \end{array}$		-	47	-	ns
Rise Time	t _r			1	18	-	
Turn-Off Delay Time	t _{d(OFF)}			1	121	-	
Fall Time	t _f			1	13	-	
Turn-On Switching Loss	E _{ON}			-	1311	-	μJ
Turn-Off Switching Loss	E _{OFF}			1	683	-	
Total Switching Loss	E _{tot}			1	1994	-	
SOURCE-DRAIN DIODE CHARACTERIST	ics						
Continuous Source-Drain Diode Forward Current	I _{SD}	$V_{GS} = -5 \text{ V}, T_J = 25^{\circ}\text{C}$		-	-	124	Α
Pulsed Source-Drain Diode Forward Current (Note 2)	I _{SDM}			-	-	363	
Forward Diode Voltage	V_{SD}	V _{GS} = -5 V, I _{SD} = 60 A, T _J = 25°C		-	4.3	-	V
Reverse Recovery Time	t _{RR}	$V_{GS} = -5/20 \text{ V}, I_{SD} = 60 \text{ A},$ $dI_{S}/dt = 1000 \text{ A}/\mu\text{s}$		-	34	-	ns
Reverse Recovery Charge	Q _{RR}			-	263	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS







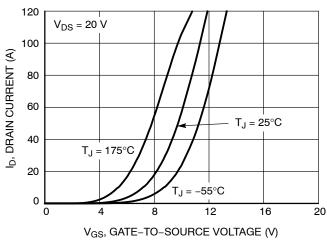


Figure 5. Transfer Characteristics

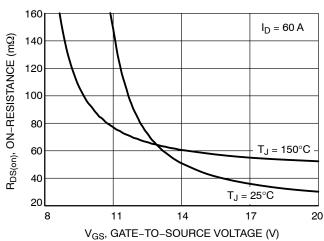
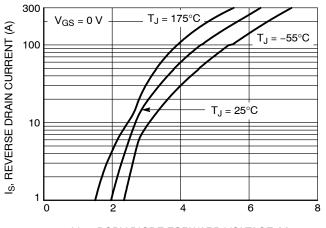


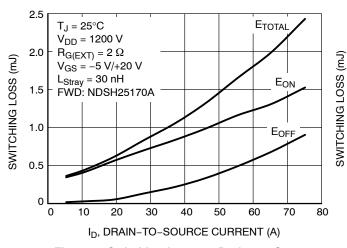
Figure 4. On-Resistance vs. Gate-to-Source Voltage



V_{SD}, BODY DIODE FORWARD VOLTAGE (V)

Figure 6. Diode Forward Voltage vs. Current

TYPICAL CHARACTERISTICS



3.0 $T_{.1} = 125^{\circ}C$ V_{DD} = 1200 V $\mathsf{E}_{\mathsf{TOTAL}}$ 2.5 $R_{G(EXT)} = 2 \Omega$ $V_{GS} = -5 \text{ V/+20 V}$ 2.0 L_{Stray} = 30 nH FWD: NDSH25170A **EON** 1.5 1.0 E_{OFF} 0.5 0 40 60 I_D, DRAIN-TO-SOURCE CURRENT (A)

Figure 7. Switching Loss vs. Drain-to-Source Current (25°C)

Figure 8. Switching Loss vs. Drain-to-Source Current (125°C)

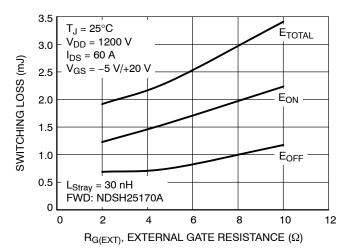
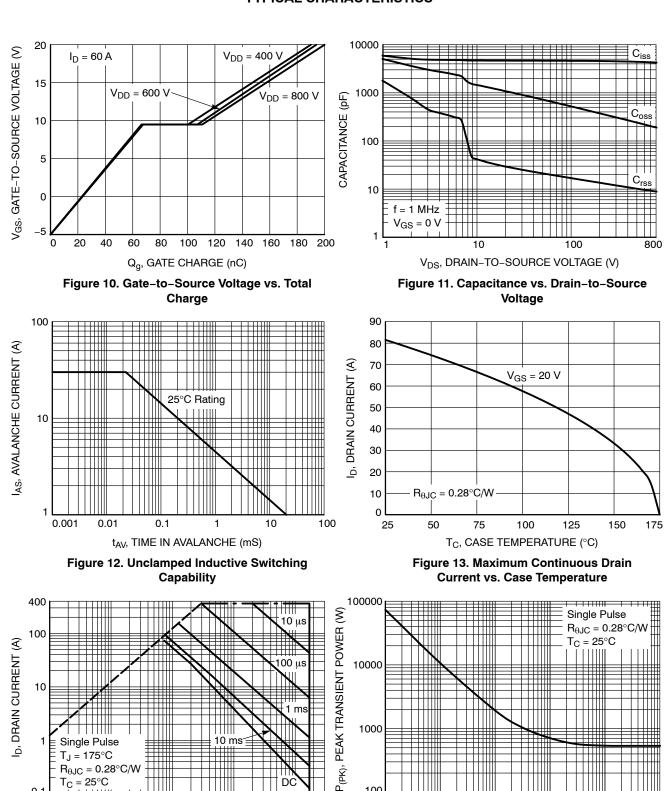


Figure 9. Switching Loss vs. External Gate Resistance

TYPICAL CHARACTERISTICS



V_{DS}, DRAIN-TO-SOURCE VOLTAGE (V) Figure 14. Safe Operating Area

10

10 ms

100

DC

1000

Single Pulse

 $T_J = 175^{\circ}C$ $R_{\theta JC} = 0.28^{\circ}C/W$ $T_C = 25^{\circ}C$

0.1

t, PULSE WIDTH (sec) Figure 15. Single Pulse Maximum Power Dissipation

0.01

0.1

0.001

1000

100

0.00001

0.0001

TYPICAL CHARACTERISTICS

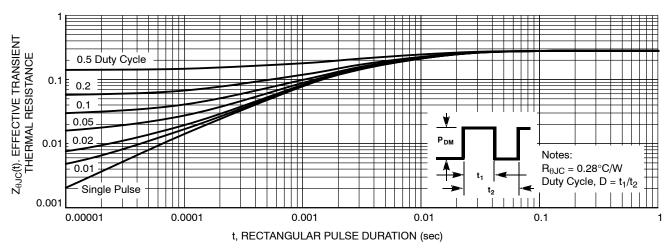
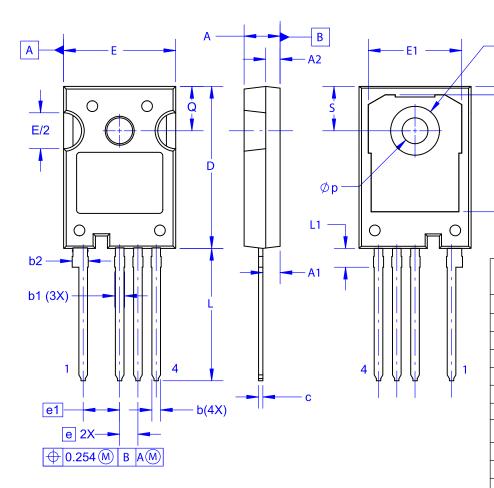


Figure 16. Junction-to-Case Thermal Response

PACKAGE DIMENSIONS

TO-247-4LD CASE 340CJ ISSUE A



NOTES:

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE.
 B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD
 FLASH, AND TIE BAR EXTRUSIONS.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.
 D. DRAWING CONFORMS TO ASME Y14.5-2009.

DIM	MIL	LIMETER	S	
DIM	MIN	NOM	MAX	
Α	4.80	5.00	5.20	
A1	2.10	2.40	2.70	
A2	1.80	2.00	2.20	
b	1.07	1.20	1.33	
b1	1.20	1.40	1.60	
b2	2.02	2.22	2.42	
С	0.50	0.60	0.70	
D	22.34	22.54	22.74	
D1	16.00	16.25	16.50	
D2	0.97	1.17	1.37	
е	2.54 BSC			
e1		5.08 BSC		
E	15.40	15.40 15.60 15.		
E1	12.80	13.00	13.20	
E/2	4.80	5.00	5.20	
L	18.22	18.42	18.62	
L1	2.42	2.62	2.82	
р	3.40	3.60	3.80	
p1	6.60	6.80	7.00	
Q	5.97	6.17	6.37	
S	5.97	6.17	6.37	

Ø**p1**

D1

D2

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